

## JIANGSU CHANGJIANG ELECTRONICS TECHNOLOGY CO., LTD

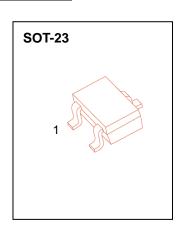
# **SOT-23 Plastic-Encapsulate Diodes**

CESD5V0AP

**ESD Protection Diodes** 

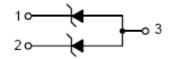
#### **DESCRIPTION**

The CESD5V0AP is designed to protect voltage sensitive components from ESD. Excellent clamping capability, low leakage, and fast response time provide best in class protection on designs that are exposed to ESD. Because of its small size, it is suited for use in cellular phones, MP3 players, digital cameras and many other portable applications where board space is at a premium.



#### **FEATURES**

- Stand-off Voltage: 3.3 V-12 V
- Low Leakage
- Response Time is Typically < 1 ns</li>
- ESD Rating of Class 3 (> 16 kV) per Human Body Model
- IEC61000-4-2 Level 4 ESD Protection
- These are Pb-Free Devices



#### Maximum Ratings @T<sub>A</sub>=25℃

Parameter	Symbol	Limits	Unit				
IEC61000-4-2(ESD)	Air		±15	KV			
	Contact		±8.0	ΝV			
ESD voltage p	er human body model		16	KV			
Total power dissipation on FR-5 board (I	$P_{D}$	225	mW				
Thermal Resistance Junction-to-Ambie	$R_{\Theta JA}$	556	°C/W				
Lead Solder Temperature - Maximum (	TL	260	℃				
Junction and Storage temperature range	T <sub>j,</sub> T <sub>stg</sub>	-55 ~ +150	°C				

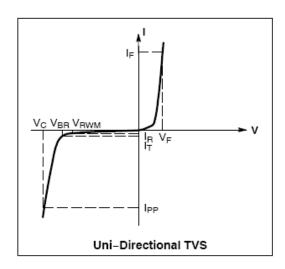
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended. Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1.  $FR-5 = 1.0 \times 0.75 \times 0.62$  in.

### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

UNIDIRECTIONAL (Circuit tied to Pins 1 and 3 or 2 and 3)

Symbol	Parameter					
I <sub>PP</sub>	Maximum Reverse Peak Pulse Current					
Vc	Clamping Voltage @ I <sub>PP</sub>					
V <sub>RWM</sub>	Working Peak Reverse Voltage					
I <sub>R</sub>	Maximum Reverse Leakage Current @ V <sub>RWM</sub>					
V <sub>BR</sub>	Breakdown Voltage @ I <sub>T</sub>					
I <sub>T</sub>	Test Current					
I <sub>F</sub>	Forward Current					
V <sub>F</sub>	Forward Voltage @ I <sub>F</sub>					
P <sub>pk</sub>	Peak Power Dissipation					
С	Max. Capacitance @V <sub>R</sub> =0 and f =1MHz					



# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted, $V_F = 0.9 \text{ V Max.} \ \text{@ } I_F = 10 \text{mA}$ for all types)

Device*	Device	V <sub>RWM</sub> (V)	I <sub>R</sub> (μ A)	V <sub>BR</sub> (V	/)	I <sub>T</sub>	Vc	Max I <sub>PP</sub> †	P <sub>pk</sub> + (W)	C (pF)
	Marking		@ <b>V</b> <sub>RWM</sub>	@ I₁(Note 2)	-1	@IPP =1 A		- рк (/	Pin 1 to 3	
	Warking	Max	Max	Min	Max	mA	٧	Α	Max	Тур
CESD3V3AP	3M3	3.3	10	5.0	5.9	1.0	7.5	13.3	300	150
CESD5V0AP	5M	5	10	6.2	7.3	1.0	9.8	12	300	110
CESD12VAP	12M	12	1.0	13.3	15.75	1.0	19	11.2	300	60

<sup>\*</sup>Other voltages available upon request.

<sup>+</sup>Surge current waveform per Figure 3

<sup>2.</sup>  $V_{\text{BR}}$  is measured with a pulse test current  $I_{\text{T}}$  at an ambient temperature of 25°C.

#### TYPICAL CHARACTERISTICS

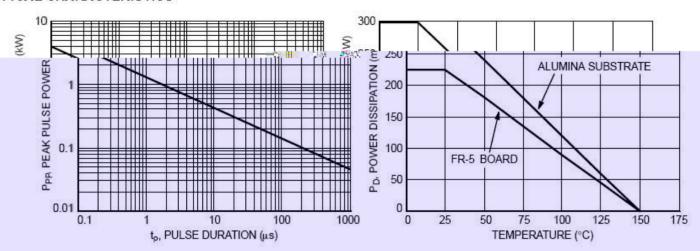


Figure 1. Non-Repetitive Peak Pulse Power versus Pulse Time

Figure 2. Steady State Power Derating Curve

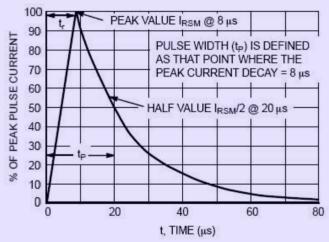


Figure 3.  $8 \times 20 \mu s$  Pulse Waveform